



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSF030NE2LQ	<b>Issued</b>	03. February 2022
<b>MA#</b>	MA000863366		
<b>Package</b>	MG-WDSO-2-3	<b>Weight*</b>	49.29 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.664	3.37	3.37	33749	33749
leadframe	non noble metal	copper	7440-50-8	45.114	91.51	91.51	915204	915204
leadfinish	non noble metal	nickel	7440-02-0	0.115	0.23		2327	
	noble metal	silver	7440-22-4	0.456	0.93	1.16	9254	11581
plating	non noble metal	nickel	7440-02-0	0.077	0.16	0.16	1571	1571
solder	non noble metal	copper	7440-50-8	0.005	0.01		106	
	noble metal	silver	7440-22-4	0.031	0.06		634	
	non noble metal	tin	7440-31-5	1.006	2.04	2.11	20404	21144
glue	miscellaneous	miscellaneous	-	0.012	0.03		253	
	plastics	acrylic resin	-	0.098	0.20		1981	
	noble metal	silver	7440-22-4	0.624	1.27	1.50	12659	14893
passivation	plastics	epoxy resin	-	0.092	0.19	0.19	1858	1858
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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